

Statement of Compliance

Requested Part

25 January 2018 1-87523-6 (Part 1 of 1)

MOD IV RECP LP

Part Status: Active

Mil-Spec Certified: No

EU RoHS: Not Compliant

Substances: Pb

EU ELV: Not Compliant

Substances: Pb

China RoHS: Restricted Materials Above Threshold

EU REACH SvHC Compliance: Regulation (EC) No. 1907/2006

Current ECHA Candidate List: JUL 2017
Candidate List Declared Against: JUL 2017

Does not contain REACH SvHCs

Halogen Content: Low Halogen - Br, Cl, F, I < 900 ppm per homogenous

material. Also BFR/CFR/PVC Free

Solder Process Capability Code: Not applicable for solder process capability

Material Declarations: MD_1-87523-6

TE Connectivity Corporation 1050 Westlakes Drive Berwyn, PA 19312

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change.

The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked.

Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV).

Regarding the REACH Regulations, TE's information on SVHC's in articles is currently based on the European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' (Version: 2, April 2011), applying the 0.1% weight to neight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 stating that, in case of 'complex articles', the threshold for a SVHC must be applied to both the product as a whole and simultaneously to each of the articles forming part of its composition. To make sure our REACH information stays in line with the changed legal interpretation and industry practices, TE is monitoring evaluations of this ruling and awaits the expected new ECHA guidance on the practical implementation.





25 January 2018

中国电子电气产品中有害物质的名称及含量

China EEP Hazardous Substance Information



Restricted Materials Above Threshold

| 部件名称 | 有害物质 | | | | | |
|------------------------------|---------------------|------|------|-------|-------|--------|
| (Component Name) | Hazardous Substance | | | | | |
| 1-87523-6 | 铅 | 汞 | 镉 | 六价铬 | 多溴联苯 | 多溴二苯醚 |
| | (Pb) | (Hg) | (Cd) | (Cr6) | (PBB) | (PBDE) |
| 连接器系统 (Connector Systems) | Х | 0 | 0 | 0 | 0 | 0 |

本表格依据SJ/T 11364标准的规定编制。

This table is compiled according to SJ/T 11364 standard.

- O: 表示该有害物质在该部件所有均质材料中的含量均在GB/T 26572标准规定的限量要求以下。
 Indicates that the concentration of the hazardous substance in all homogeneous materials of the part is below the relevant threshold of the GB/T 26572 standard.
- X: 表示该有害物质至少在该部件的某一均质材料中的含量超出GB/T 26572标准规定的限量要求。
 Indicates that the concentration of the hazardous substance in at least one homogeneous material of the part is above the relevant threshold of the GB/T 26572 standard.

电子电气产品的环保使用期限依据SJ/T 11388标准的规定确定。

The EFUP value of EEP is defined according to SJ/T 11388 standard.



RoHS Equivalent Part(s) for Part 1-87523-6

25 January 2018 **2-87523-4** (Equivalent Part 1 of 1)

MOD IV RECP LP

Part Status: Active

Mil-Spec Certified: No

EU RoHS: Compliant

EU ELV: Compliant

China RoHS: No Restricted Materials Above Threshold

EU REACH SvHC Compliance: Regulation (EC) No. 1907/2006

Current ECHA Candidate List: **JUL 2017**Candidate List Declared Against: **JUL 2017**

Does not contain REACH SvHCs

Halogen Content: Not Low Halogen - contains Br or CI > 900 ppm.

Solder Process Capability Code: Not applicable for solder process capability